

WHAT IS CLAIMED IS:

1. A resin composition for encapsulating a semiconductor chip comprising:

5 an epoxy resin (A);

a phenol resin (B);

an inorganic filler (C);

a curing accelerator (D);

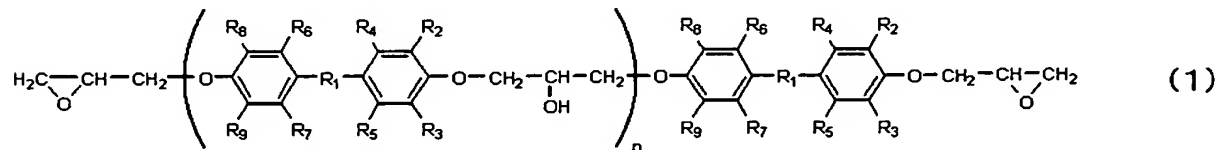
a silane coupling agent (E); and

10 Compound (F) containing two and more hydroxyl groups combined with each of adjacent carbon atoms comprising an aromatic ring.

2. The resin composition for encapsulating a semiconductor chip according to Claim 1, wherein the resin composition comprises
15 said compound (F) in more than or equal to 0.01 wt%.

3. The resin composition for encapsulating a semiconductor chip according to Claim 1, wherein the resin composition comprises said silane coupling agent (E) in 0.01 wt% to 1 wt% both inclusive.

4. The resin composition for encapsulating a semiconductor
20 chip according to Claim 1, wherein said epoxy resin (A) comprises an epoxy resin represented by general formula (1):



wherein R_1 represents a single bond or saturated or
unsaturated hydrocarbon having up to three carbon atoms; R_2 to R_9 ,
25 which may be the same or different from each other, represent hydrogen

or saturated hydrocarbon having up to four carbon atoms; and n is a positive number more than 0 and up to 5 as an average, in 50 wt% or more.

5 5. The resin composition for encapsulating a semiconductor chip according to Claim 1, wherein said Compound (F) contains two hydroxyl groups combined with each of adjacent carbon atoms comprising said aromatic ring.

10 6. The resin composition for encapsulating a semiconductor chip according to Claim 1, wherein the aromatic ring is a naphthalene ring.

7. The resin composition for encapsulating a semiconductor chip according to Claim 6, wherein said Compound (F) contains two hydroxyl groups combined with each of adjacent carbon atoms comprising said naphthalene ring.

15 8. The resin composition for encapsulating a semiconductor chip according to Claims 1, wherein the resin composition comprises said inorganic filler (C) in 80 wt% to 94 wt% both inclusive.

20 9. A semiconductor device wherein a semiconductor chip is encapsulated by the use of a resin composition for encapsulating a semiconductor chip according to Claims 1.